

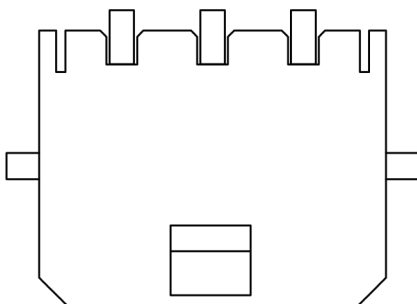
# WAFER CONNECTOR SMT TYPE

3001 SERIES - 3.00MM

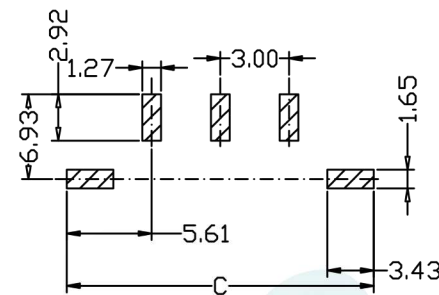


## Specifications

- Rated current: 5.0AMP
- Voltage rating: 250V AC/DC
- Contact resistance: 20mΩ max
- Withstand Voltage: 1500V AC/minute
- Insulation resistance: 1000MΩ min
- Operation temperature: -40°C to +105°C
- Contact material: Brass
- Contact plating: Tin Over Ni
- Solder Tabs material: Brass/Tin plated
- Insulator material: Polyester (UL94V-0)
- Standard: LCP
- Max. processing Temp: 230°C for 30-60 seconds  
260°C for 10 seconds



Recommended P.C.B Layout (Top Side)  
(PCB BOARD TOLERANCE ±0.05)



## Ordering Information

**3001S1** - (XX) X X (1)

1                    2                    3                    4

### 1. Connector Series

### 2. Number of pins per row (02→12)

### 3. Insulator Material Option

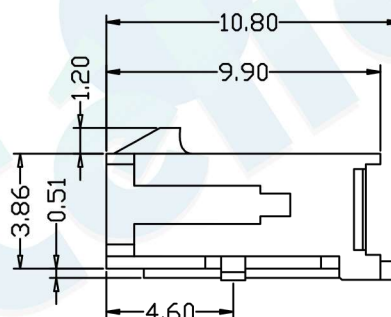
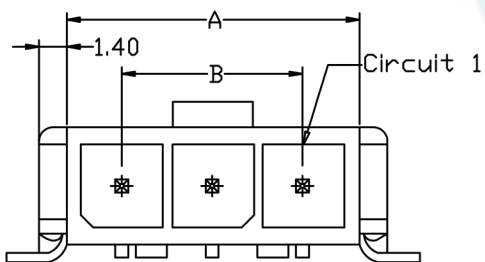
- A = BK-PA6T
- B = BK-PA9T
- C = BK-LCP

### 4. Contact plating

- A = Gold Flash
- B = Gold Flash/Tin
- C = Tin
- D = Matte-Tin

#### (1). Packaging

Ø=Pe Bag 1=Tube 2=Reel



Poles	Dimensions		
	A	B	C
2	6.85	3.00	14.20
3	9.85	6.00	17.20
4	12.85	9.00	20.20
5	15.85	12.00	23.20
6	18.85	15.00	26.20
7	21.85	18.00	29.20
8	24.85	21.00	32.20
9	27.85	24.00	35.20
10	30.85	27.00	38.20
11	33.85	30.00	41.20
12	36.85	33.00	44.20

				OPERATION		DRAW	BEN	12.04.18	SCALE	FIT	 votre partenaire en électronique		
				X.X	±0.30				UNIT	mm			
				X.XX	±0.20	CHECK		SIZE	A4	PART NO.			3001S1 - XXXX
				X.XXX	±0.10	APPROVE		SHEET	1/1				
A0	2012.04.18	NEW DRAWING		Angle	±3°			PROJ.	◆	TITLE:			MX3.00mm Wafer 1xNpin SMT
REV	DATE	MODIFICATION DESCRIPTION	CHANGE	DIM	TOL								